

LL4001G THRU LL4007G

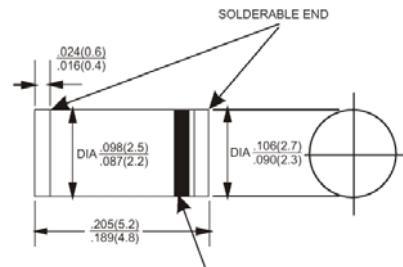
SURFACE MOUNT GLASS PASSIVATED SILICON RECTIFIERS

Reverse Voltage - 50 to 1000 V

Forward Current - 1 A

Features

- For surface mounted applications
- High temperature metallurgically bonded construction



Mechanical data

- **Case:** Molded plastic, MELF (DO-213AB)
- **Polarity:** Color band denotes cathode end
- **Mounting position:** Any

Plastic case MELF (DO-213AB)
Dimensions in inches and (millimeters)

Maximum Ratings and Electrical characteristics

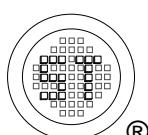
Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbols	LL4001G	LL4002G	LL4003G	LL4004G	LL4005G	LL4006G	LL4007G	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T _A = 75°C	I _{F(AV)}				1				A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}				30				A
Maximum Forward Voltage at 1 A	V _F				1.1				V
Maximum Reverse Current T _A = 25°C at Rated DC Blocking Voltage T _A = 125°C	I _R				5				µA
Typical Junction Capacitance ¹⁾	C _J				15				pF
Typical Thermal Resistance ²⁾	R _{θJA}				50				°C/W
Typical Thermal Resistance ³⁾	R _{θJT}				20				°C/W
Operating Junction Temperature Range	T _j				- 55 to + 150				°C
Storage Temperature Range	T _{stg}				- 55 to + 150				°C

¹⁾ Measured at 1 MHz and applied reverse voltage of 4 V D.C

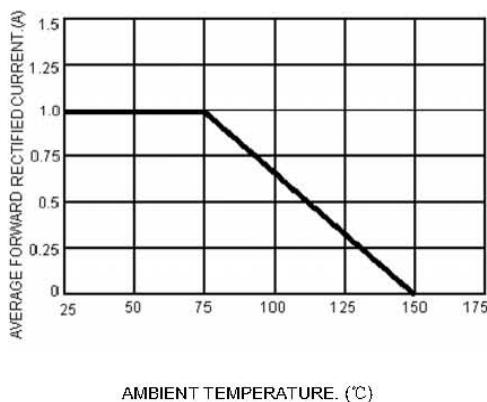
²⁾ Thermal resistance from junction to ambient, 0.24 X 0.24" (6 X 6 mm) copper pads to each terminal

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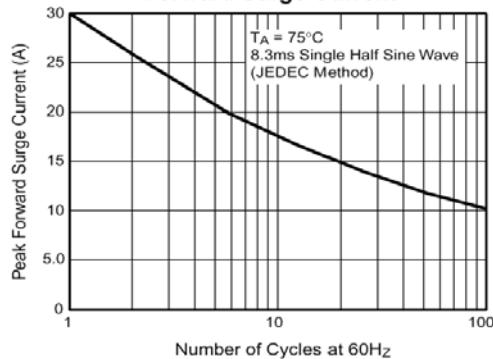
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FIG.1 -MAXIMUM FORWARD CURRENT DERATING CURVE



AMBIENT TEMPERATURE, (°C)

Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current



T_A = 75°C
8.3ms Single Half Sine Wave
(JEDEC Method)

Fig. 3 - Typical Instantaneous Forward Characteristics

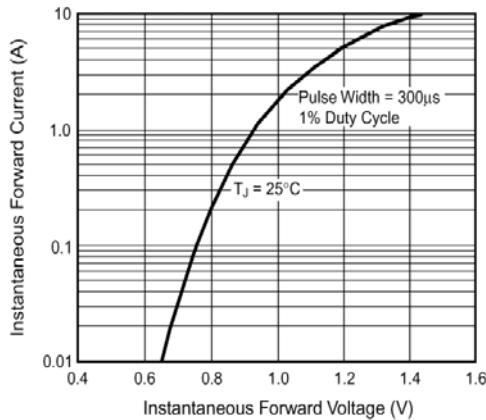
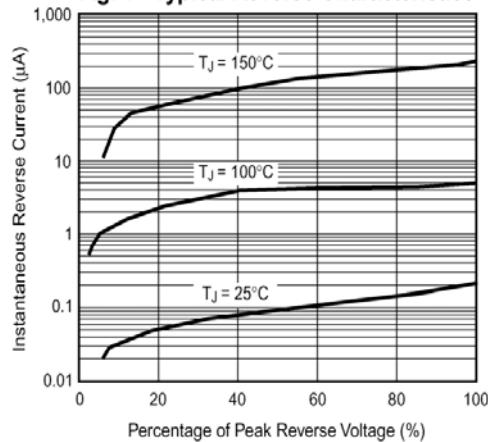


Fig. 4 –Typical Reverse Characteristics



T_J = 150°C
T_J = 100°C
T_J = 25°C

Fig. 5 – Typical Junction Capacitance

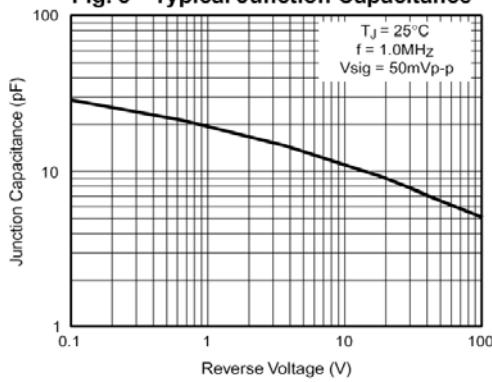
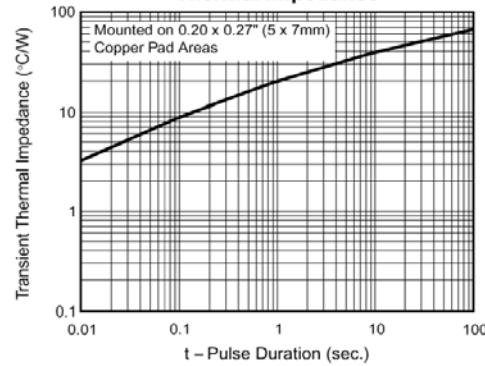


Fig. 6 - Typical Transient Thermal Impedance



Mounted on 0.20 x 0.27" (5 x 7mm)
Copper Pad Areas

